

OL-NX3DV1066

wafer level chip-size package; 16 bumps

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	10-1-2012

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.33	-	1.36	1.39	mm
E	package width	1.33	-	1.36	1.39	mm
A	seated height	0.405	-	4.35	0.465	mm
A ₂	package height	0.28	-	0.305	0.33	mm
e	nominal pitch	-	-	0.35	-	mm
n ₂	actual quantity of termination	-	-	16	-	

2. Package outline

Fig. 1. Package outline WLCSP (OL-NX3DV1066)



3. Legal information

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